



To the Honorable Commissioner of Patents

102078720

attached original documents or copy thereof

1. Name of Conveying Part(ies):

Brian A. Vaartstra

Additional name(s) of conveying party(ies) attached?

Yes  No

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Internal Address:

Street Address: 8000 South Federal Way

City: Boise State: ID Zip: 83716

3. Nature of conveyance:

- Assignment
- Merger
- Other
- Security Agreement
- Change of Name

Execution Date: 4/16/02

Additional names(s) & address(es) attached:  Yes  No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 4/16/02

A. Patent Application No.(s):

B. Patent No.(s)

Additional numbers attached:  Yes  No

Additional numbers attached:  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David G. Latwesen, Ph.D.

Internal Address:  
Wells St. John P.S.

Street Address: 601 W. First Avenue, Ste. 1300

City: Spokane State: WA Zip: 99201-3828

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number

23-0925

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is the original document.

David G. Latwesen, Ph.D.

Name of Person Signing

Signature

4/25/02

Date

TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS AND DOCUMENT:     

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**PATENT ASSIGNMENT****PARTIES TO THE ASSIGNMENT:****INVENTOR:**

Brian A. Vaartstra

**ASSIGNEE:**

Micron Technology, Inc.  
Corporation of the State of Delaware  
8000 South Federal Way  
Boise, Idaho 83716

**BACKGROUND OF THIS ASSIGNMENT:**

INVENTOR has conceived certain new and useful inventions disclosed in a United States patent application titled "Atomic Layer Deposition Methods and Chemical Vapor Deposition Methods".

MICRON TECHNOLOGY, INC. (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

**THE PARTIES AGREE AS FOLLOWS:**

In consideration of good and valuable consideration, the receipt sufficiency and adequacy of which is hereby acknowledged, INVENTOR hereby sells, assigns and transfers to ASSIGNEE the entire right and interest in the above-identified application executed concurrently with this assignment and to any reissues, renewals, divisions or continuations thereof, and hereby authorizes the

Commissioner of Patents and Trademarks to issue such Letters Patent to ASSIGNEE for the sole use of ASSIGNEE, its successors or assigns.


INVENTOR further agrees to execute, at the request and expense of ASSIGNEE such other formal documents as may be required to fully convey the interest transferred herein and will similarly execute any application papers required for the filing of any division, continuation, renewal or reissue of the patent application or resulting Letters Patent; and will generally do everything necessary or desirable to obtain and enforce proper protection for the invention assigned hereby.

INVENTOR further assigns to ASSIGNEE the whole right, title and interest in the inventions disclosed in the application throughout all countries foreign to the United States. ASSIGNEE is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International Convention; to file and prosecute International Applications relating to the inventions under the Patent Cooperation Treaty; and to file and prosecute applications relating to the inventions under the European Patent Convention. INVENTOR agrees to execute applications relating to the inventions in those countries and under those conventions where it is necessary that the same be executed by the inventor, and to execute assignments of such applications and the resulting Letters Patent to ASSIGNEE as well as all other necessary papers in relation to such applications and Letters Patent.

INVENTOR further warrants and covenants that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full rights to convey the same as herein expressed is possessed by the undersigned.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignees.

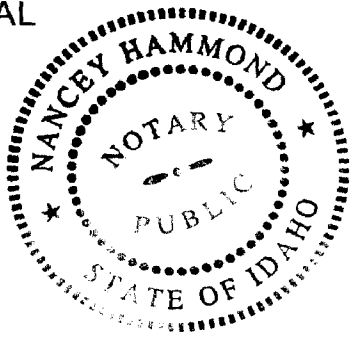
Dated: 04/16/02

Signature:   
Brian A. Vaartstra

State of Idaho )  
County of Ada ) ss.

BEFORE ME, this 16th day of April, 2002, personally appeared the above-named inventor, known to me to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he executed the same of his own free will for the purpose therein expressed.

SEAL



Nancy Hammond  
Notary or Consular Officer  
My Commission Expires: 6/12/03